

A cross-sectional view of a semiconductor device. A substrate 10 is shown with a series of electrodes 14 and passivation layers 16. The electrodes 14 are formed on the bottom surface of the substrate 10, and the passivation layers 16 are formed on the top surface of the substrate 10. The electrodes 14 are connected to the passivation layers 16.

A cross-sectional view of a semiconductor device 10. The device consists of a substrate 12 with a metal layer 14 and a patterned layer 16. The patterned layer 16 is formed on the metal layer 14 and has a series of rectangular openings 18. A label "Metal" points to the metal layer 14.

(B)

10

16

18

20

14

14

14

Polymer

This diagram shows a cross-section of a polymer film. The film has a wavy interface between two layers. The top layer is labeled 10. The bottom layer is labeled 14. The wavy interface is labeled 16. The top surface of the bottom layer is labeled 18. The bottom surface of the bottom layer is labeled 20. The word "Polymer" is written below the bottom layer.

(C)

10

14

16

18

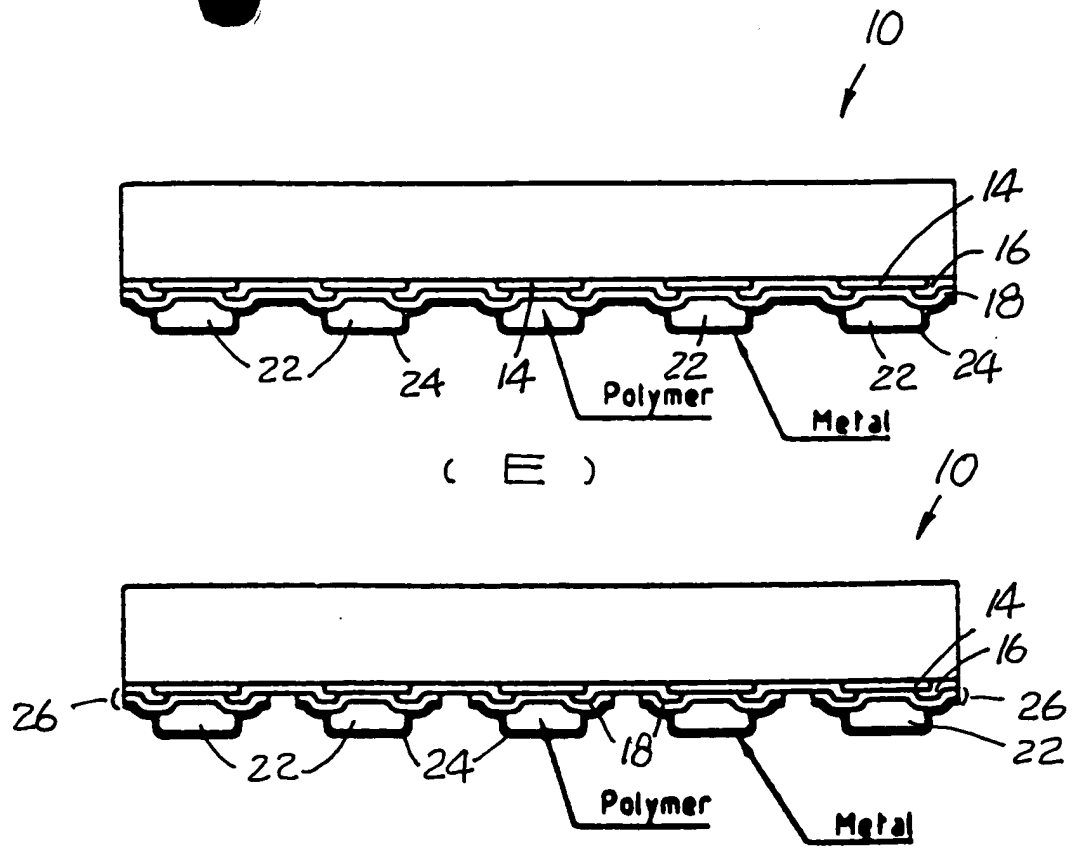
22

Polymer

This diagram shows a cross-section of a polymer film. The film has a flat top surface (14) and a corrugated bottom surface (16). The corrugations are formed by a series of rectangular protrusions (22) that are spaced apart. The material is labeled as 'Polymer'.

Fig 1 (Prior Art)

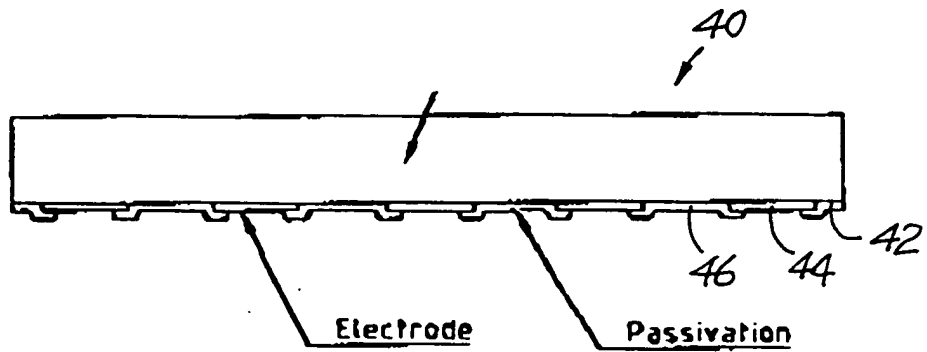
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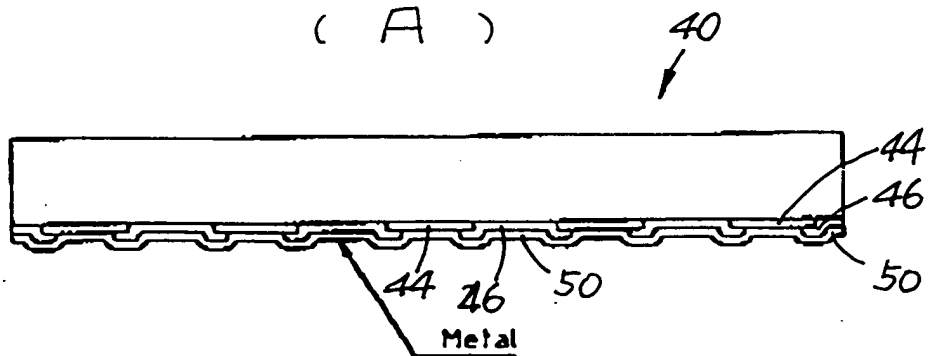
(E)

(F)

FIG 1 (Prior Art)

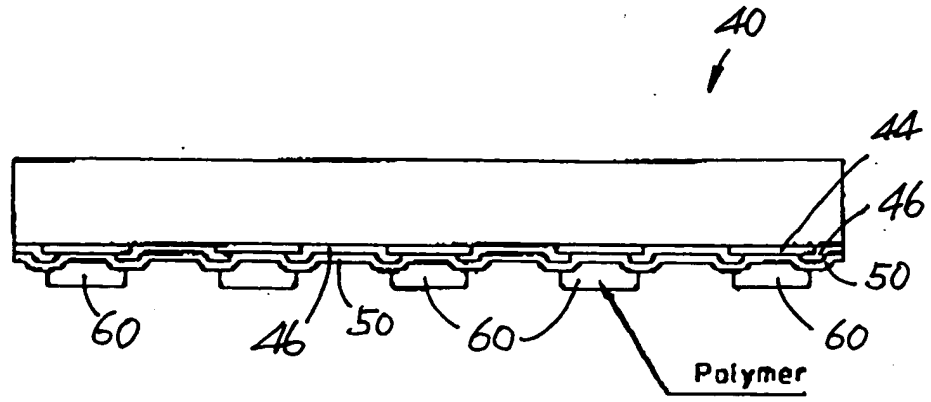


(A)

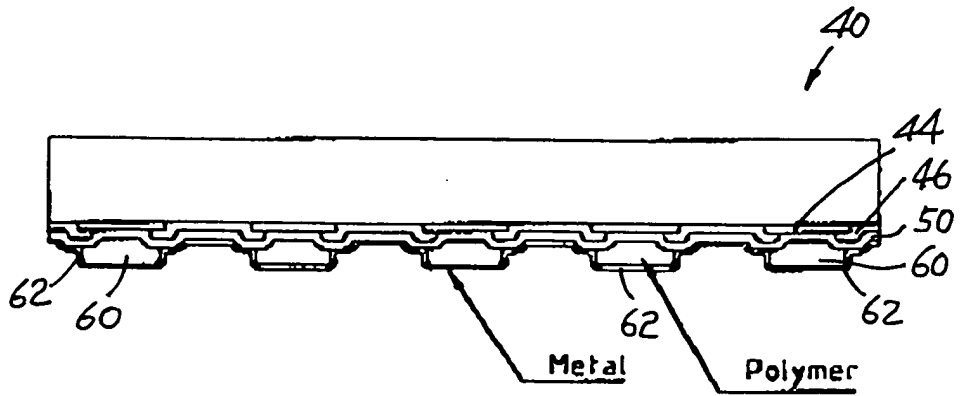


(B)

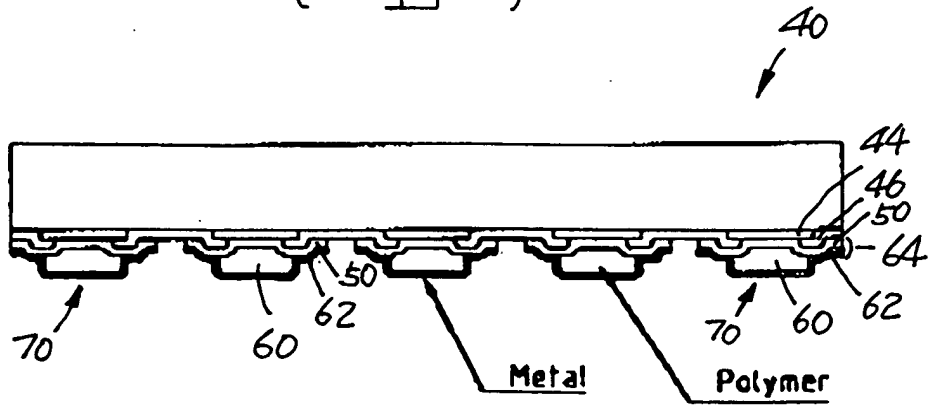
FIG 2



(C)



(D)



(E)

